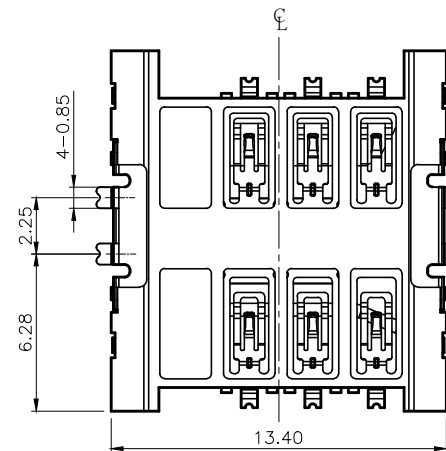
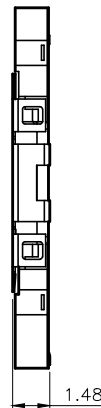
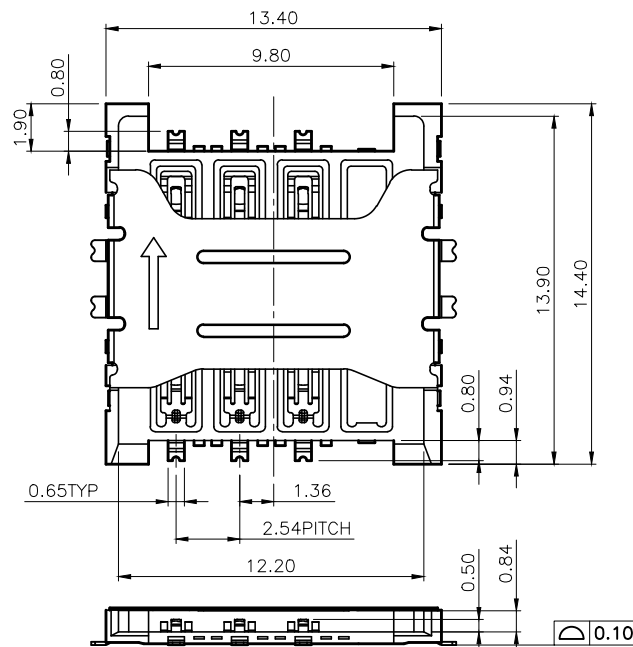


REV.	ECN.NO.	MODIFY.CONTENT	DATE
A		NEW	2015/03/29

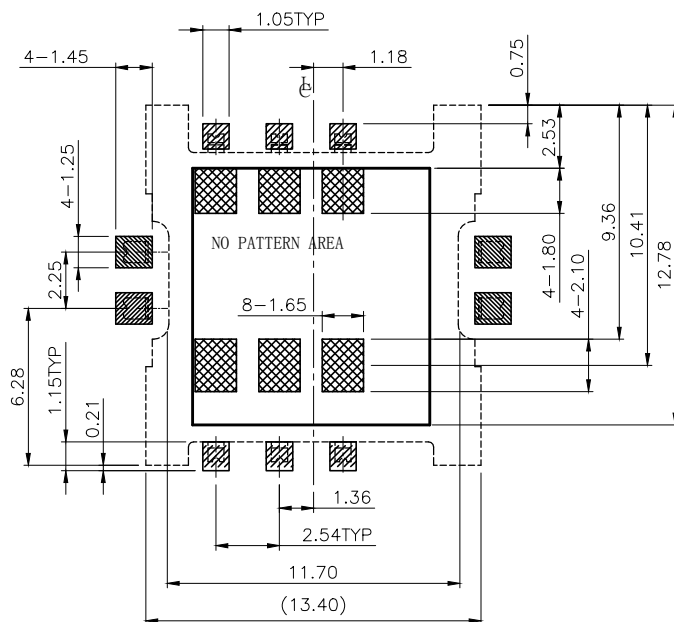


MATERIALS

- HOUSING : THERMOPLASTIC (UL 94V-0) .
- TERMINAL : COPPER ALLOY,
PLATING : GOLD PLATED ON CONTACT AREA
AND SOLDER TAILS,NICKEL PLATED OVERALL.
- SHELL : STAINLESS STEEL.
PLATING : NICKEL PLATED OVERALL.
GOLD PLATED ON SOLDER TAILS

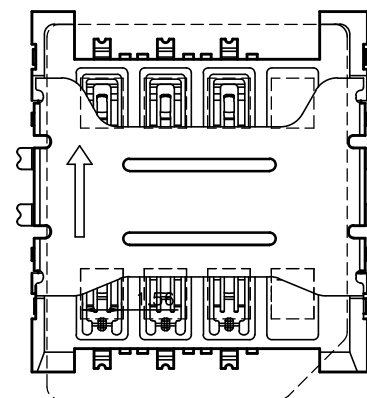
SPECIFICATION

- CURRENT RATING : 1.0 A MAX.
- DIELECTRIC WITHSTANDING VOLTAGE :
500V AC R.M.S. FOR ONE MINUTE.
- INSULATION RESISTANCE : 1000M次MIN. AT 500V DC.
- CONTACT RESISTANCE : 30m次MAX.
- OPERATING TEMPERATURE : -40°C TO +85°C.



RECOMMENDED P.C.B. LAYOUT
TOLERANCE:±0.05 TOP VIEW

- PCB AREA
- CONNECT AREA
- KEEP OUT AREA



DESCRIPTION OF PLATING ON TERMINALS

NO.	EXPLAIN	NO.	EXPLAIN
0	GOLD FLASH	3	GOLD 15u"
1	GOLD 5u"	4	GOLD 20u"
2	GOLD 10u"	6	GOLD 30u"

GENERAL TOLERANCE		DWG NO.	JYSA0422-001	APPD:	WIND	Scale	1:1
X.±0.45	x.'±5'	Title	MICRO SIM SOCKET 6PIN 1.50H (焊接脚外折防溃PIN)	CHKD:		UNIT	mm
.X±0.35	.x'±2'			DR:			
.XX±0.25	.xx'±1'	Part NO.	JYS-SIM150-117	Date	2015/03/29		
.XXX±0.15	.xxx'±0.5'	杰宇森电子有限公司 JIE YU SEN ELECTRONIC CO., LTD.					
SHEET	1/1						